

Application Serial No: 10/579,573
Responsive to the Office Action mailed on: June 14, 2007

REMARKS

This Amendment is in response to the Office Action mailed on June 14, 2007.

Claims 1, 2 and 4 are amended. Claim 1 and 4 are amended editorially and are supported, for example, in the specification on page 8, lines 8-24, page 10, lines 12-25 and in Figure 1. Claim 2 is amended editorially to track the features of claim 1. No new matter is added. Claims 1-4 are pending.

§102 Rejections:

Claim 1 is rejected as being anticipated by Takeda (JP Publication No. 2002-175952). This rejection is traversed. Claims 1, 2 and 4 are rejected as being anticipated by Yabushita (JP Publication No. 2002-043175). These rejections are traversed.

Claim 1 is directed to a surface-mount solid electrolytic capacitor that requires, among other features, an anode lead terminal and a cathode lead terminal, each formed with a first standing piece with the first standing piece of the anode terminal being spaced from the anode. The anode lead terminal is also formed with a second standing piece in contact with the anode within the resin package. An advantage of these features is that the anode is prevented from being exposed at a package surface during the manufacturing process.

Neither Takeda nor Yabushita disclose or suggest these features. Takeda is directed to a lead frame for a capacitor. The rejection asserts that the capacitor of Takeda includes an anode lead terminal (7) and a cathode lead terminal (6) (see Figure 7b). The rejection also asserts that the anode lead terminal (7) and the cathode lead terminal (6) include standing pieces at portions corresponding to the side surfaces of the package (3). Takeda may be interpreted as having first standing pieces at portions corresponding to the side surfaces of the package (3). However, nowhere does Takeda disclose or suggest that the anode lead terminal (7) is formed with a first standing piece and a second standing piece or that the second standing piece is in contact with the anode within the resin package. Also, nowhere does Takeda disclose or suggest the standing piece of the anode lead terminal (7) being spaced from an anode. Furthermore, nowhere does Takeda contemplate preventing the anode from being exposed at a package during the

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manufacturing process by using a second standing piece in contact with the anode within the resin package.

Yabushita is directed to a chip type solid-state electrolytic capacitor. The rejection asserts that the capacitor of Yabushita includes an anode lead terminal (6, 7) and a cathode lead terminal (8, 9) (see Figure 2) with the elements (7) and (9) representing the standing pieces of claim 1. The elements (7) and (9) may be interpreted as the first standing pieces of claim 1. However, nowhere does Yabushita disclose or suggest that the anode lead terminal (6, 7) is formed with a first standing piece and a second standing piece or that the second standing piece is in contact with the anode within the resin package. Also, nowhere does Yabushita disclose or suggest the standing piece of the anode lead terminal (6, 7) being spaced from an anode. Furthermore, nowhere does Yabushita contemplate preventing the anode from being exposed at a package during the manufacturing process by using a second standing piece in contact with the anode within the resin package. For at least these reasons claim 1 is not suggested by Takeda or Yabushita. Claim 2 depends from claim 1 and should be allowed for at least the same reasons.

Claim 4 is directed to a method for manufacturing a surface-mount solid electrolytic capacitor that requires, inter alia, forming a second standing piece at the anode lead terminal of the lead frame. Claim 4 also requires the step of mounting a capacitor element onto the anode lead terminal and the cathode lead terminal, respectively, while the anode contacts the second standing piece. An advantage of these steps is that the anode is prevented from being exposed at a package surface during the manufacturing process.

Yabushita does not disclose or suggest these features. As discussed above, with respect to claim 1, the rejection asserts that the capacitor of Yabushita includes an anode lead terminal (6, 7) and a cathode lead terminal (8, 9) (see Figure 2) with the elements (7) and (9) representing the standing pieces of claim 1. The elements (7) and (9) may be interpreted as the first standing pieces of claim 1. However, nowhere does Yabushita disclose or suggest forming a second standing piece at the anode lead terminal of the lead frame. Also, nowhere does Yabushita disclose or suggest the mounting a capacitor element onto the anode lead terminal and the cathode lead terminal, respectively, while

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the anode contacts the second standing piece. Furthermore, nowhere does Yabushiata contemplate preventing the anode from being exposed at a package during the manufacturing process by using a second standing piece in contact with the anode within the resin package. For at least these reasons claim 4 is not suggested by Takeda or Yabushita.

Conclusion:

Applicant respectfully asserts that claims 1-4 are in condition for allowance. If a telephone conference would be helpful in resolving any issues concerning this communication, please contact Applicant's primary attorney-of record, Douglas P. Mueller (Reg. No. 30,300), at (612) 455-3804.

Respectfully submitted,



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